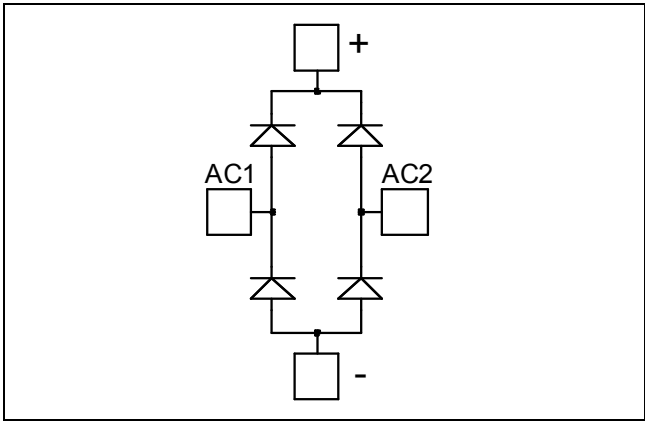


## Diode Full Bridge Power Module

**$V_{RRM} = 1200V$**   
 **$I_C = 200A @ T_c = 60^\circ C$**

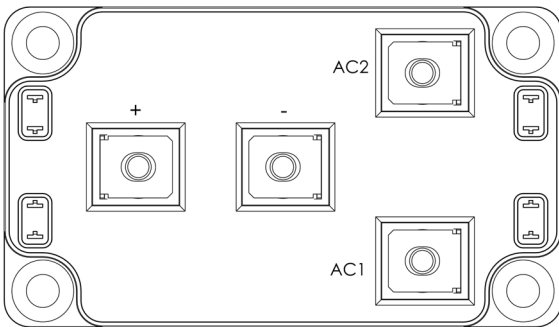


### Application

- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

### Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
- High level of integration



### Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

**All ratings @  $T_j = 25^\circ C$  unless otherwise specified**

### Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
$V_R$	Maximum DC reverse Voltage	1200	V
$V_{RRM}$	Maximum Peak Repetitive Reverse Voltage		
$I_{F(AV)}$	Maximum Average Forward Current	Duty cycle = 50%	235
			$T_C = 25^\circ C$
$I_{F(RMS)}$	RMS Forward Current	Duty cycle = 50%	200
			$T_C = 60^\circ C$
$I_{FSM}$	Non-Repetitive Forward Surge Current	8.3ms	1500
			$T_C = 45^\circ C$

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

**Electrical Characteristics**

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> = 200A			2.4	3.0	V
		I <sub>F</sub> = 300A			2.7		
		I <sub>F</sub> = 200A	T <sub>j</sub> = 125°C		1.8		
I <sub>RM</sub>	Maximum Reverse Leakage Current	V <sub>R</sub> = 1200V	T <sub>j</sub> = 25°C			150	μA
			T <sub>j</sub> = 125°C			600	
C <sub>T</sub>	Junction Capacitance	V <sub>R</sub> = 1200V			220		pF

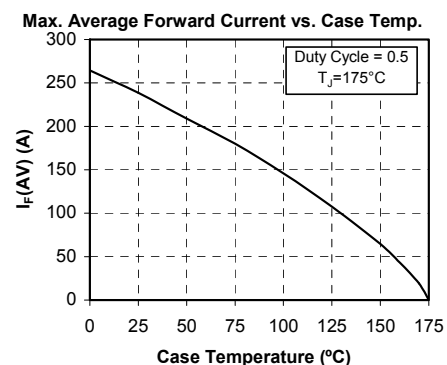
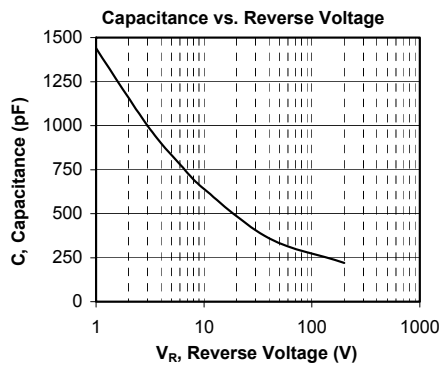
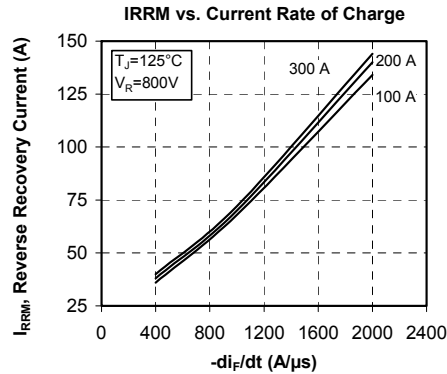
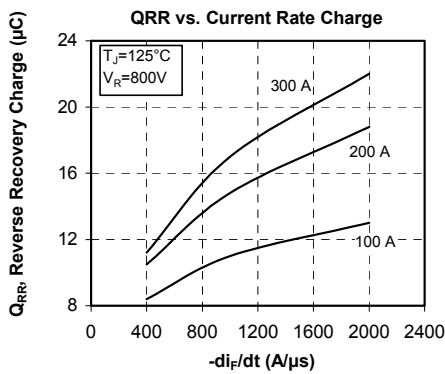
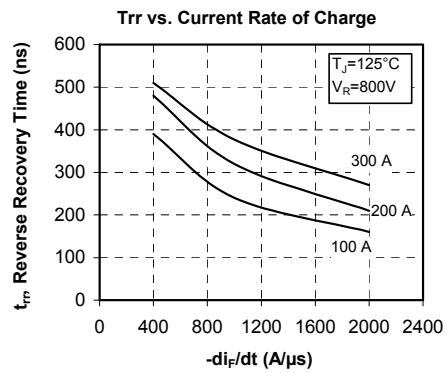
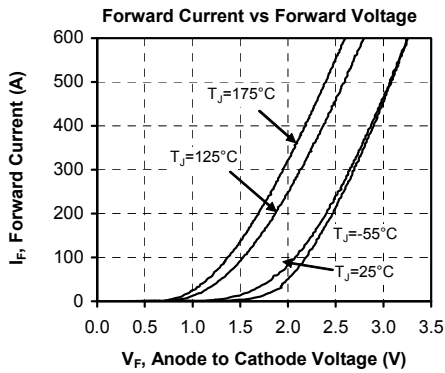
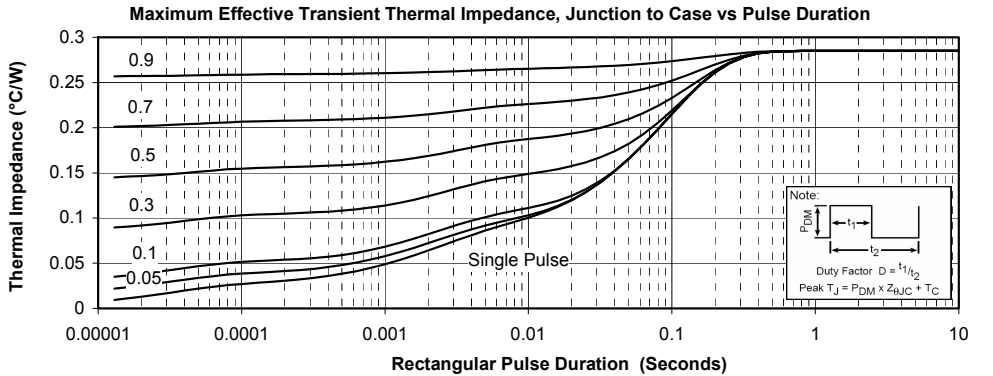
**Dynamic Characteristics**

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =1A, V <sub>R</sub> =30V	T <sub>j</sub> = 25°C		45		ns	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 200A V <sub>R</sub> = 800V di/dt = 400A/μs	T <sub>j</sub> = 25°C		385		ns	
			T <sub>j</sub> = 125°C		480			
Q <sub>rr</sub>	Reverse Recovery Charge		T <sub>j</sub> = 25°C		2.1		μC	
			T <sub>j</sub> = 125°C		10.5			
I <sub>R</sub> RM	Reverse Recovery Current		T <sub>j</sub> = 25°C		12		A	
			T <sub>j</sub> = 125°C		38			
t <sub>rr</sub>	Reverse Recovery Time		I <sub>F</sub> = 200A V <sub>R</sub> = 800V di/dt=2000A/μs	T <sub>j</sub> = 125°C		210		ns
Q <sub>rr</sub>	Reverse Recovery Charge					19		μC
I <sub>R</sub> RM	Reverse Recovery Current				140		A	

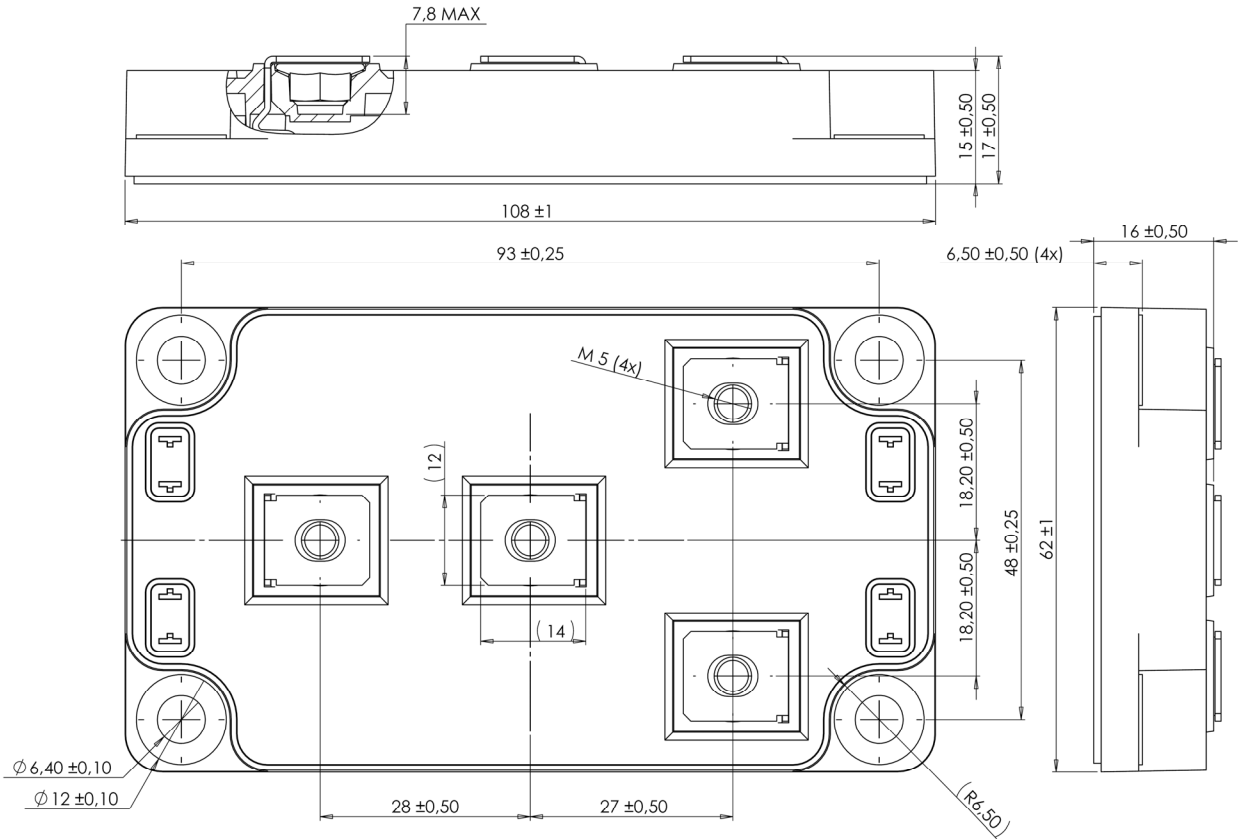
**Thermal and package characteristics**

<i>Symbol</i>	<i>Characteristic</i>			<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R <sub>thJC</sub>	Junction to Case Thermal Resistance					0.285	°C/W
V <sub>ISOL</sub>	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T <sub>J</sub>	Operating junction temperature range			-40		175	°C
T <sub>STG</sub>	Storage Temperature Range			-40		125	
T <sub>C</sub>	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
		For terminals	M5	2		3.5	
Wt	Package Weight					300	g

## Typical Performance Curve



**SP6 Package outline** (dimensions in mm)



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